

12/30/05
Atty Ref/Docket No.: 884.F94US1

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01-12-2006

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Patent and Trademark Office

To the Honorable Commissioner of Patent

103156256

attached original documents or copy thereof.

1. Name of conveying party(ies):

Heeman Choe and Daewoong Suh

Additional name(s) of conveying party(ies) attached?

[] Yes [X] No

3. Nature of conveyance:

[X] Assignment [] Merger

[] Security Agreement [] Change of Name

[] Other

Execution Date: December 27, 2005 and December 23, 2005, respectively

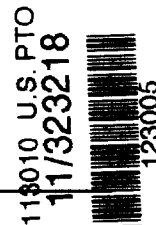
2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95052

Additional name(s) & address(es) attached? [] Yes [X] No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: December 27, 2005 and December 23, 2005, respectively

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? [] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ann M. McCrackin

Address:
Schwegman, Lundberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

[] Enclosed

[X] Authorized to be charged to deposit account

8. Please charge any additional fees or credit any over payments to our Deposit account number: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ann M. McCrackin/Reg. No. 42,858

Name of Person Signing

Ann M. McCrackin 11/11/2005 LMUELLER 00000094 190743 11323218
Signature Date

Total number of pages including cover sheet: 5

Mail documents to be recorded with required cover sheet information to:

Mail Stop Assignment Recordation Services
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PATENT
REEL: 017414 FRAME: 0223

ASSIGNMENT

H.C.
26 Majolica Pl., The Woodlands, TX

77382 WHEREAS, We, Heeman Choe, residing at ~~25335 Budde Rd. #411, Spring, TX~~
~~77380~~, and Daewoong Suh, residing at 16821 S. 1st Drive, Phoenix, AZ 85045, made certain
new and useful inventions and improvements for which we executed an application for Letters
Patent of the United States on even date herewith, which is entitled SOLDER FOAMS, NANO-
POROUS SOLDERS, FOAMED-SOLDER BUMPS IN CHIP PACKAGES, METHODS OF
ASSEMBLING SAME, AND SYSTEMS CONTAINING SAME;

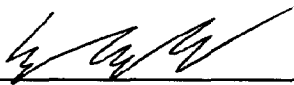
AND WHEREAS, Intel Corporation, a corporation organized and existing under and by
virtue of the laws of the State of Delaware, and having an office and place of business at 2200
Mission College Blvd., Santa Clara, CA 95052 (hereinafter "Assignee"), is desirous of acquiring
the entire right, title and interest in and to said inventions, improvements and application and in
and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and
valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have
sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said
Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all
inventions and improvements disclosed in the aforesaid application, and in and to the said
application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters
Patent which may be granted there from, and all reissues or extensions of such patents, and in
and to any and all applications which have been or shall be filed in any foreign countries for
Letters Patent on the said inventions and improvements, including an assignment of all rights
under the provisions of the International Convention, and all Letters Patent of foreign countries
which may be granted there from; and we do hereby authorize and request the Commissioner of
Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid
inventions and improvements to the said Assignee as the assignee of the entire right, title and
interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and
legal representatives will make, execute and deliver any and all other instruments in writing
including any and all further application papers, affidavits, assignments and other documents,
and will communicate to said Assignee, its successors and representatives all facts known to us
relating to said improvements and the history thereof and will testify in all legal proceedings and
generally do all things which may be necessary or desirable more effectually to secure to and
vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said
improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and
advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore, we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this Tues day of Dec 27, 2005.



Heeman Choe

IN TESTIMONY WHEREOF, I have hereunto set my hand this _____ day of _____, 2005.

Daewoong Suh

ASSIGNMENT

WHEREAS, We, Heeman Choe, residing at 25335 Budde Rd. #411, Spring, TX 77380, and Daewoong Suh, residing at 16821 S. 1st Drive, Phoenix, AZ 85045, made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States on even date herewith, which is entitled SOLDER FOAMS, NANO-POROUS SOLDERS, FOAMED-SOLDER BUMPS IN CHIP PACKAGES, METHODS OF ASSEMBLING SAME, AND SYSTEMS CONTAINING SAME;

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2200 Mission College Blvd., Santa Clara, CA 95052 (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency whereof is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignee, its successors or assigns, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted there from, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted there from; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to the said Assignee as the assignee of the entire right, title and interest in and to the same, for the use of the said Assignee, its successors and assigns.

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignee, its successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignee, its successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

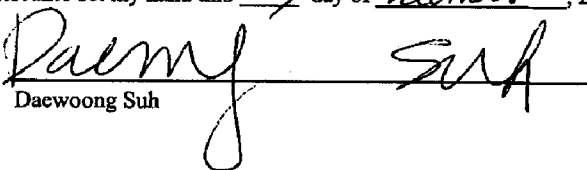
Docket No: 884.F94US1
Serial Number : Not Assigned
Filing Date : even date herewith
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AND, furthermore, we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this ____ day of _____, 2005.

Heeman Choe

IN TESTIMONY WHEREOF, I have hereunto set my hand this 23 day of December, 2005.


Daewoong Suh